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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/657,415	09/08/2003	Elissa E. Carapella	42P6139CD	9024

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EXAMINER

NGUYEN, DONGHAI D

ART UNIT	PAPER NUMBER
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3729

SHORTENED STATUTORY PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE
3 MONTHS	01/24/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

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Office Action Summary	Application No. 10/657,415	Applicant(s) CARAPPELLA ET AL.	
	Examiner Donghai D. Nguyen	Art Unit 3729	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 10/30/06 and Panel Decision on 12/06/06.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 17, 18, 24-32, 36, 37, 41 and 45-48 is/are pending in the application.
- 4a) Of the above claim(s) 24-30 is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 17, 18, 31, 32, 36, 37, 41, 44, 45, 47 and 48 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Response to Amendment

1. The amendment filed on October 30, 2006 has been considered and made of record. In view of Panel decision made on December 6, 2006, the Finally of the Office Action, dated 08/01/06 is hereby withdrawn and following is a new Office Action based on the amendment filed on October 30, 2006.

Claim Rejections - 35 USC § 112

2. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter, which the applicant regards as his invention.

3. Claims 36, 37 and 48 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

“the side surface” (claim 36, line 6) lacks antecedent basis. It’s suggested to be changed to: --the inside surface--.

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) The invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

5. Claims 17, 18, 31, 32 and 41 are rejected under 35 U.S.C. 102(b) as being anticipated by US Patent 5,825,084 to Lau et al.

Regarding claim 17, Lau et al disclose a method of forming an integrated circuit package, comprising: providing a package housing having a first bonding pads (110' in Fig. 2A or 210 in Fig 4B) located on a first bond shelf (100, 200 etc.), the bond shelf including top surface and a first edge (See Figs. 2A and 4B); forming a first conductive strip (215 one surface of the central portion 105, see Fig 4B) along the first edge of the first bond shelf, the conductive strip wrapping around and over the first edge of the first bond shelf to electrically couple a first bonding pad (top bonding pad 210 in fig. 4B) of the first plurality of bonding pads (210) on the first the bond shelf to a first power bus (140) under the first bond shelf (see Fig. 2A); and forming a second conductive strip (215 to the left or right of the central portion 205) along the first edge of the first bond shelf the second conductive strip wrapping around and over the first edge of the first bond shelf to electrically couple a second bonding pad (the left or right bonding pad shown in Fig. 4B) of the first plurality of bonding pads (210) on the first bond shelf to a second power bus (different power bus 140 see Fig. 2C) under the first bond shelf, the second power having a second voltage level less than the first voltage level of the first bus (see Col. 4, lines 41-44 discloses at least two voltage levels ground and power therefore second power bus maybe a ground voltage) and located with the first power bus in a same horizontal plane (bottom surface of the bonding shelf 200 or 500, see Figs 2 and 6) of the integrated circuit package.

Regarding claim 18, Lau et al disclose the conductive strip is formed by plating (Col. 5, lines 39-41).

Regarding claim 31, Lau et al disclose a method of forming an integrated circuit package, comprising: providing a package housing having a first bond shelf (100, 200 etc.) with a top surface and an inside surface (See Figs. 2A, 4B); forming a conductive material (215 see Fig. 4B) along the inside surface of the first bond shelf, a first portion of the conductive material wrapping around from the inside surface onto the top surface of the first bond shelf (Col. 4, lines 38-40) to form a plurality of bonding pads (110' or 210) on the top surface of the bond shelf (See Figs. 2A and 4C); and, removing a second portion (130 see Fig. 2A and Col. 5, lines 60-63) of the conductive material along the inside surface of the bond shelf to form a pair of separate conductive strips along the inside surface of the bond shelf (see Figs. 2A, 3D, 4D) with a first conductive strip (middle strip 215' in Fig. 4D) of the pair of conductive strips coupled to a first bonding pad of the plurality of bonding pads coupled to a first power bus (140) and a second conductive strip (right strip 215' in Fig. 4D) of the pair of conductive strips coupled to a second bonding pad of the plurality of bonding pads coupled to a second power bus (another 140 see Fig. 2C), the second power bus having a second voltage level less than the first voltage level of the first bus (see Col. 4, lines 41-44 discloses at least two voltage levels ground and power therefore second power bus maybe a ground voltage) and located with the first power bus in a same horizontal plane (bottom surface of the bonding shelf 200 or 500, see Figs 2 and 6) of the integrated circuit package.

Regarding claim 32, Lau et al disclose the conductive strip is formed by plating (Col. 5, lines 39-41).

Regarding claim 36, Lau et al disclose a method of forming an integrated circuit package (see Fig. 1B), comprising: providing a package housing having a rectangular bond shelf (100,

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200 etc.) with a rectangular top surface and an inside surface perpendicular with the top surface (See Figs. 2A, 4B), the bond shelf having a plurality of bonding pads (110/210) located on the top surface; forming a conductive material (Col. 5, lines 32-33) along the inside surface of the bond shelf, a first portion of the conductive material wrapping around from the inside surface onto the top surface of the bond shelf (Col. 4, lines 38-40) to couple to at least one of the first plurality of bonding pads on the top surface of the bond shelf (See Fig. 4C); and, removing a second portion (130) of the conductive material along the inside surface of the bond shelf to form a pair of separate conductive strips along the inside surface of the bond shelf (see Figs. 2A, 3D, 4D) with a first conductive strip (middle strip 215' in Fig. 4D) of the pair of conductive strips coupled to a first bonding pad of the plurality of bonding pads coupled to a first power bus (140) and a second conductive strip (right strip 215' in Fig. 4D) of the pair of conductive strips coupled to a second bonding pad of the plurality of bonding pads coupled to a second power bus (another 140 see Fig. 2C), the second power bus having a second voltage level less than the first voltage level of the first bus (see Col. 4, lines 41-44 discloses at least two voltage levels ground and power therefore second power bus maybe a ground voltage) and located with the first power bus in a same horizontal plane (bottom surface of the bonding shelf 200 or 500, see Figs 2 and 6) of the integrated circuit package.

Regarding claim 37, Lau et al disclose the conductive strip is formed by plating (Col. 5, lines 39-41).

Regarding claim 41, Lau et al disclose forming the conductive strips by removing a portion of conductive strip (Col. 5, lines 60-63).

Claim Rejections - 35 USC § 103

6. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

7. Claims 44,45, 47 and 48 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lau et al in view of Applicant Admitted Prior art (AAPA).

Lau et al disclose the first bus and second bus having different second voltage except the actual voltage levels of the first and second buses. However, AAPA teaches that the different voltage levels are required in some integrated circuit such as 3.3 volts and 2.0 volts (Spec. page 2, lines 15-17). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the power buses of Lau et al (about 100 power and ground buses in the same plane see Col. 6, lines 46-50) to carry different voltage levels as taught by AAPA for supplying power to the integrated circuit that requires different voltage level depending on the layout and features of the IC device to be formed in the integrated package (see Col. 4, lines 41-47).

Response to Arguments

8. Applicants' arguments with respect to claims 17, 18, 31, 32 36, 37 41, 44, 45, 47 and 48 have been considered but are moot in view of the new ground(s) of rejection.

9. Applicants' arguments filed October 30, 2006 have been fully considered but they are not persuasive. Applicants argue, "the combined teachings of Lau et al and AAPA do not establish a

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prima facie case of obviousness” (see “Remarks” page 9, last paragraph) in this Office Action for claims 44, 45, 47 and 48. The Examiner disagrees because Lau et al teach the different voltage levels are applicable when the IC to be mounted in the integrated package required the different voltage levels (see Col. 4, lines 41-47) and AAPA teaches such IC that requires different voltage levels such as 2.0 and 3.3 volts (see Applicants Specification page 2, lines 15-25).

Conclusion

10. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Donghai D. Nguyen whose telephone number is (571)-272-4566. The examiner can normally be reached on Monday-Friday (9:00-6:00).

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Peter D. Vo can be reached on (571)-272-4690. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

DN

January 11, 2007


MINH TRINH
PRIMARY EXAMINER